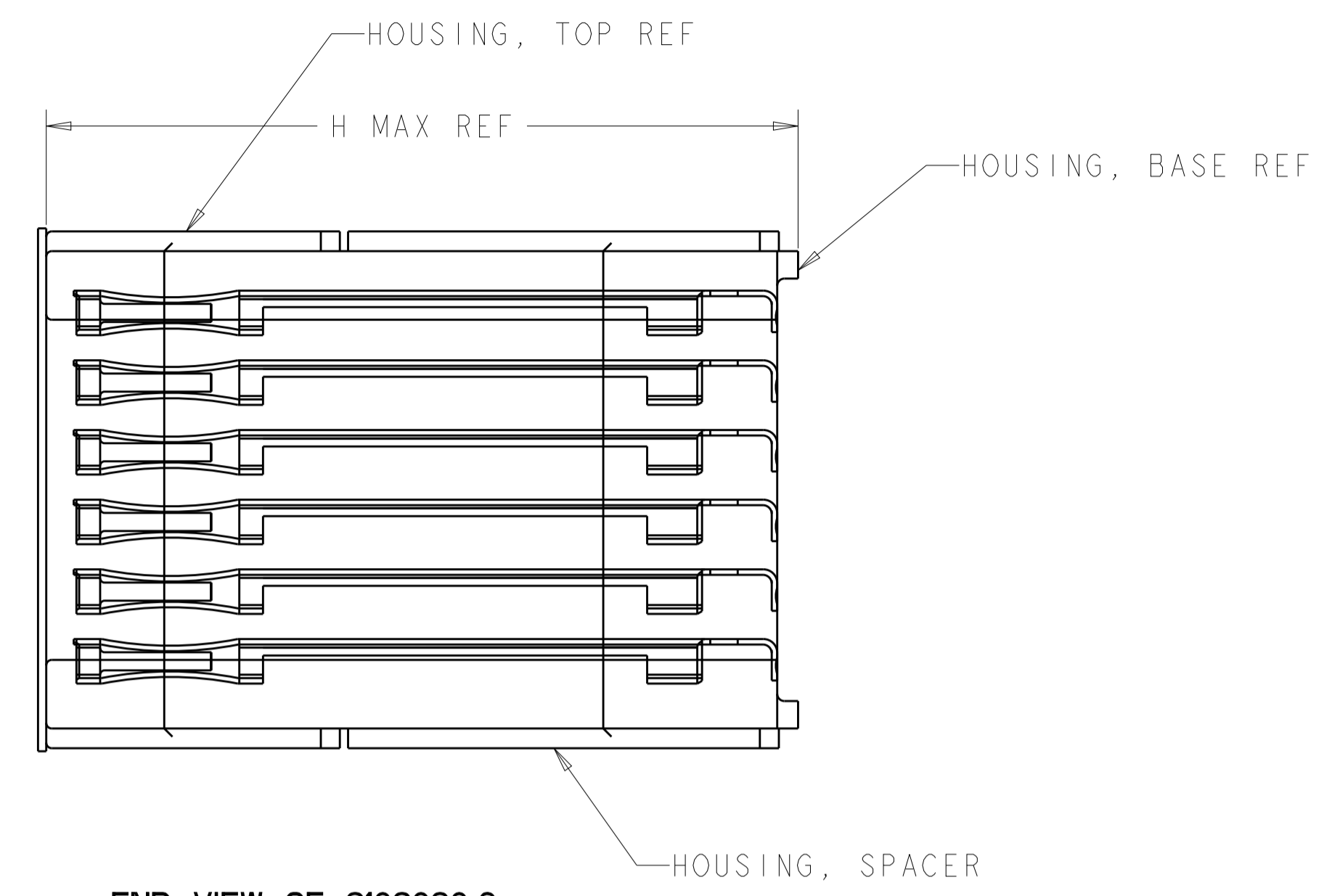
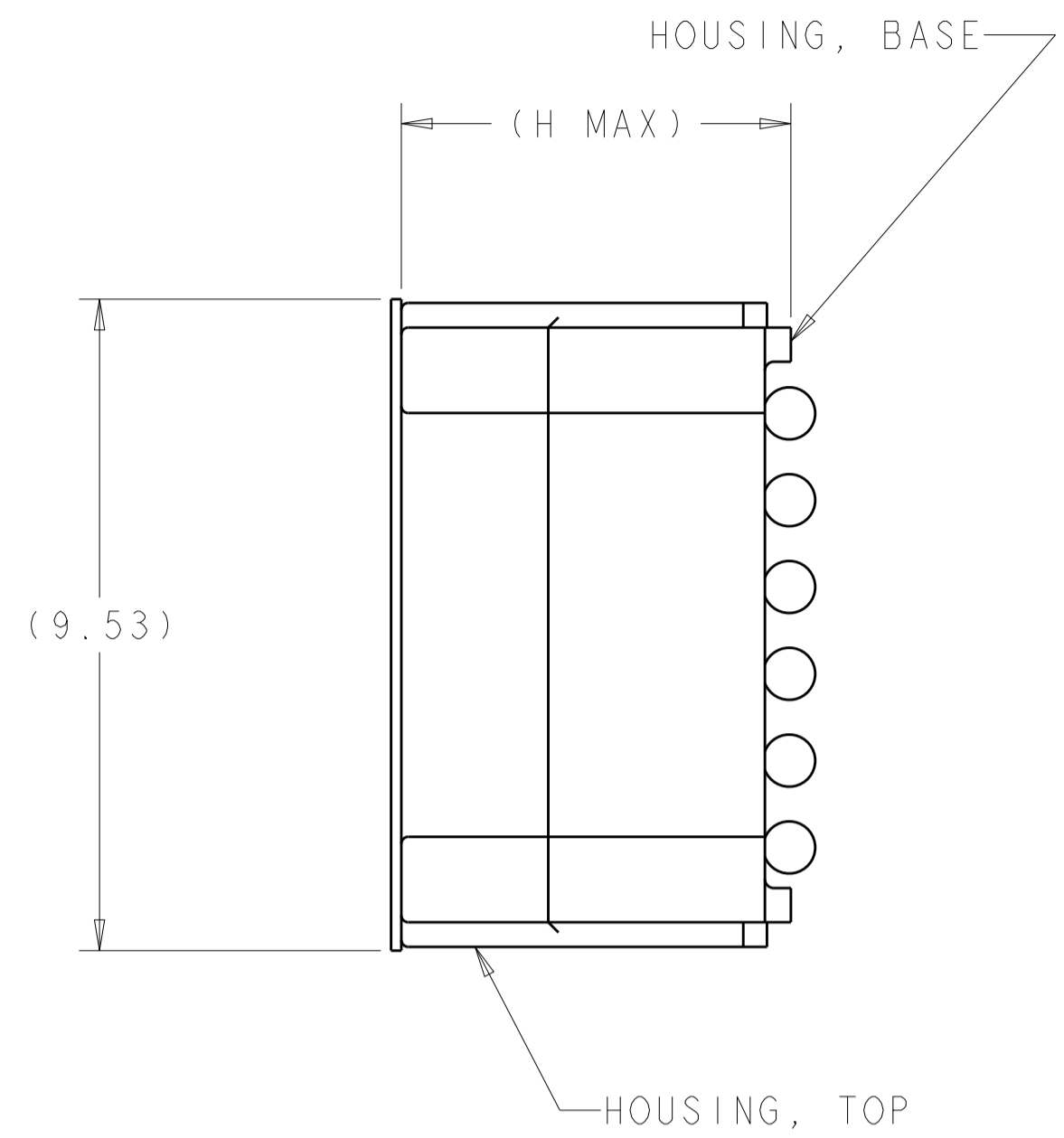
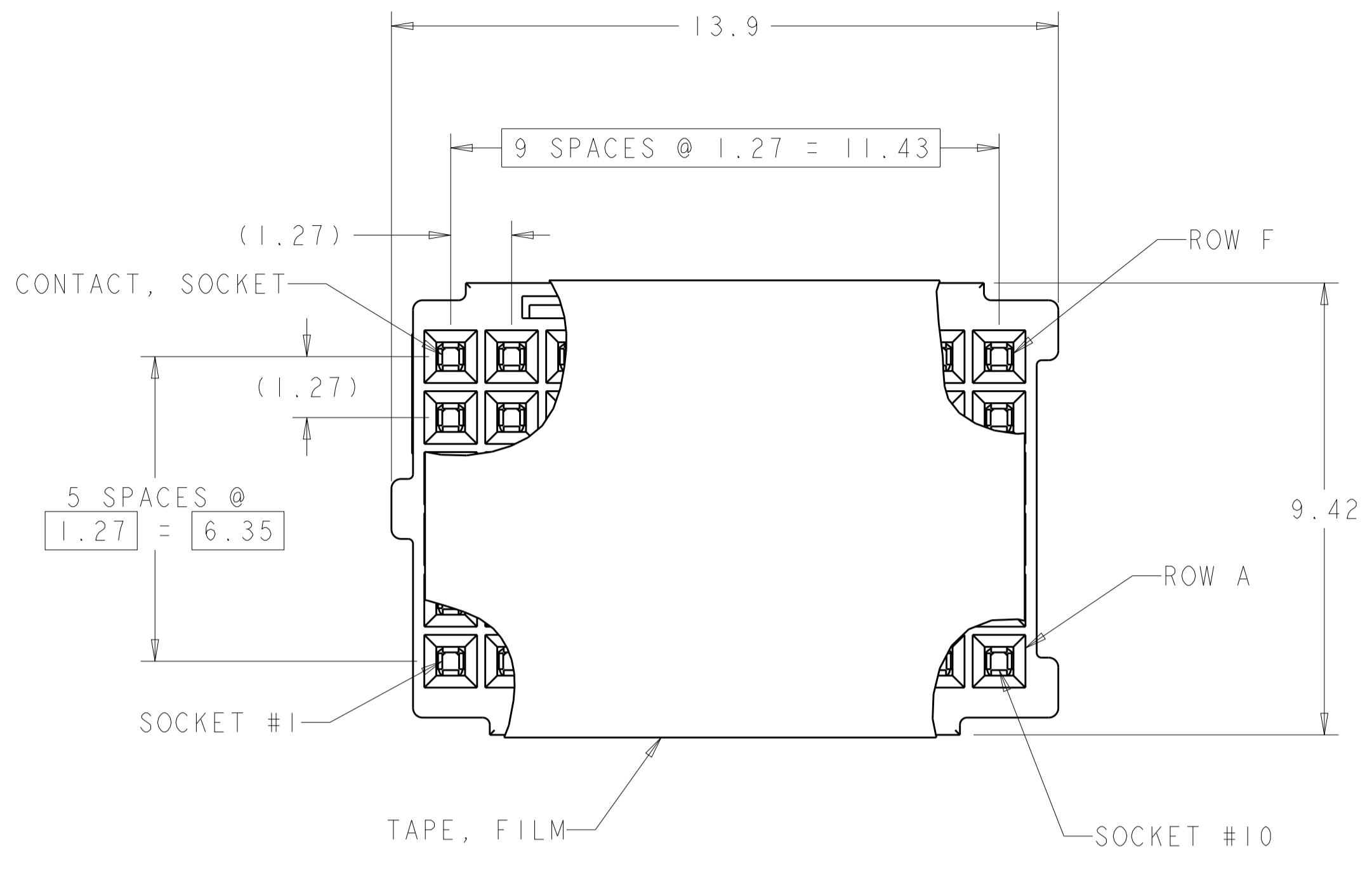
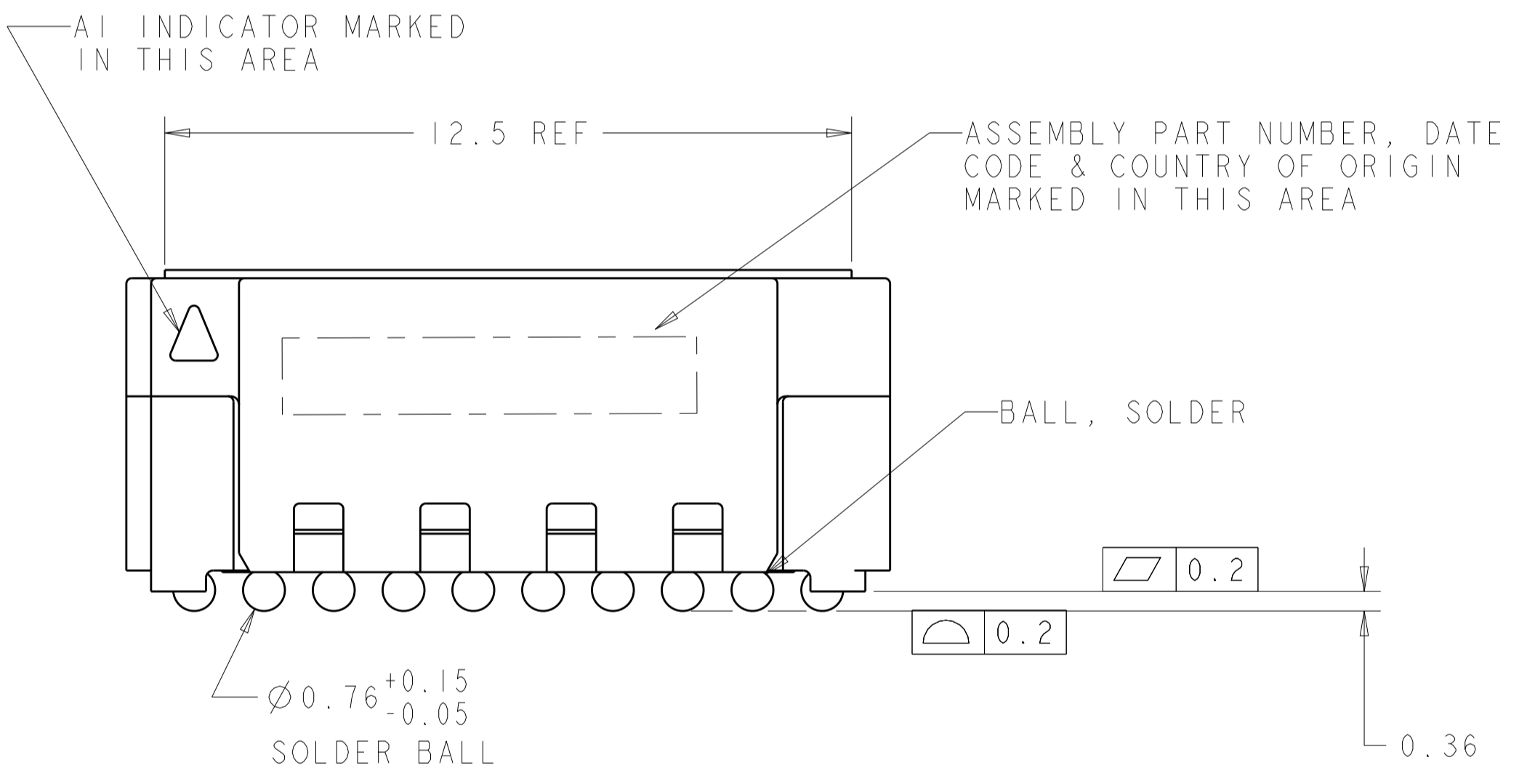
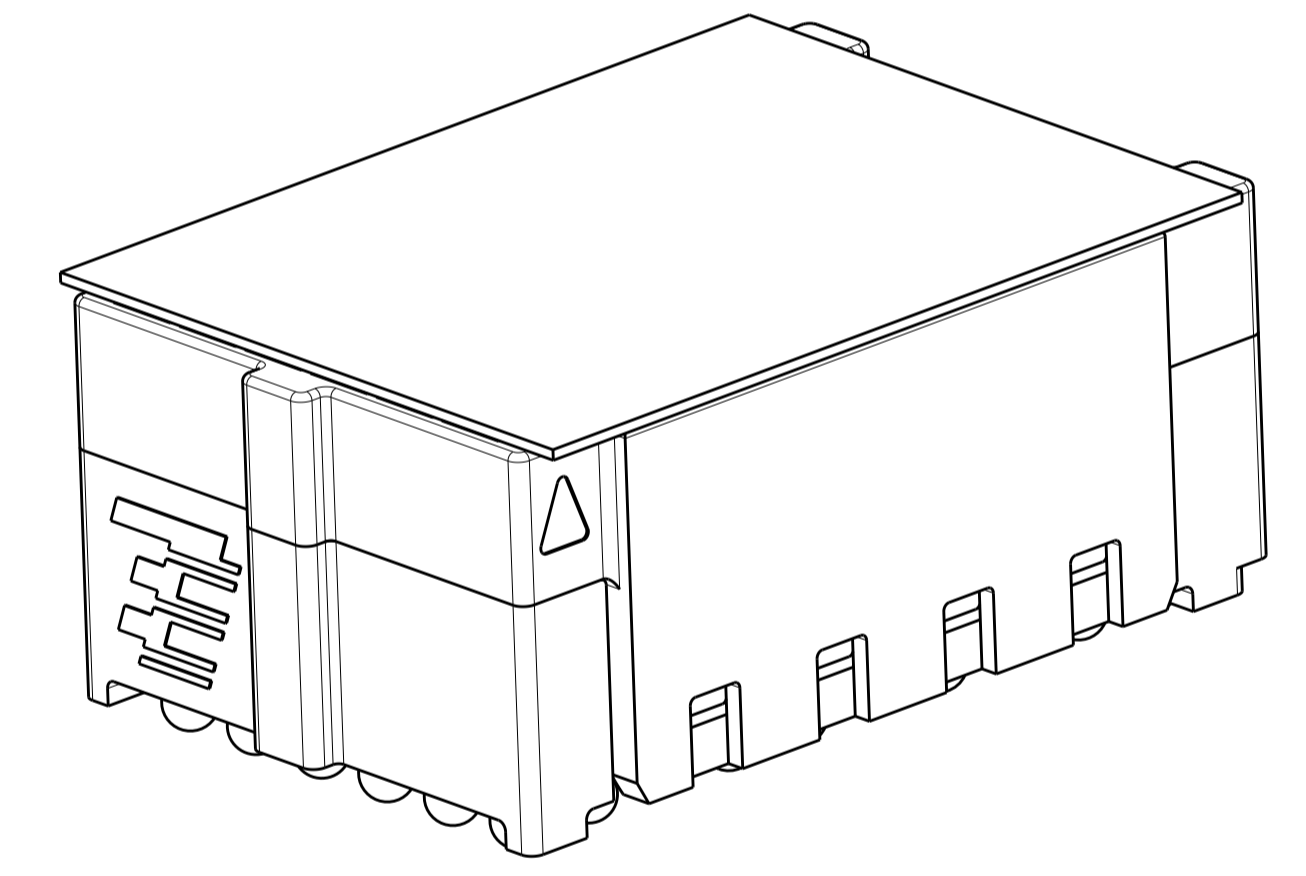


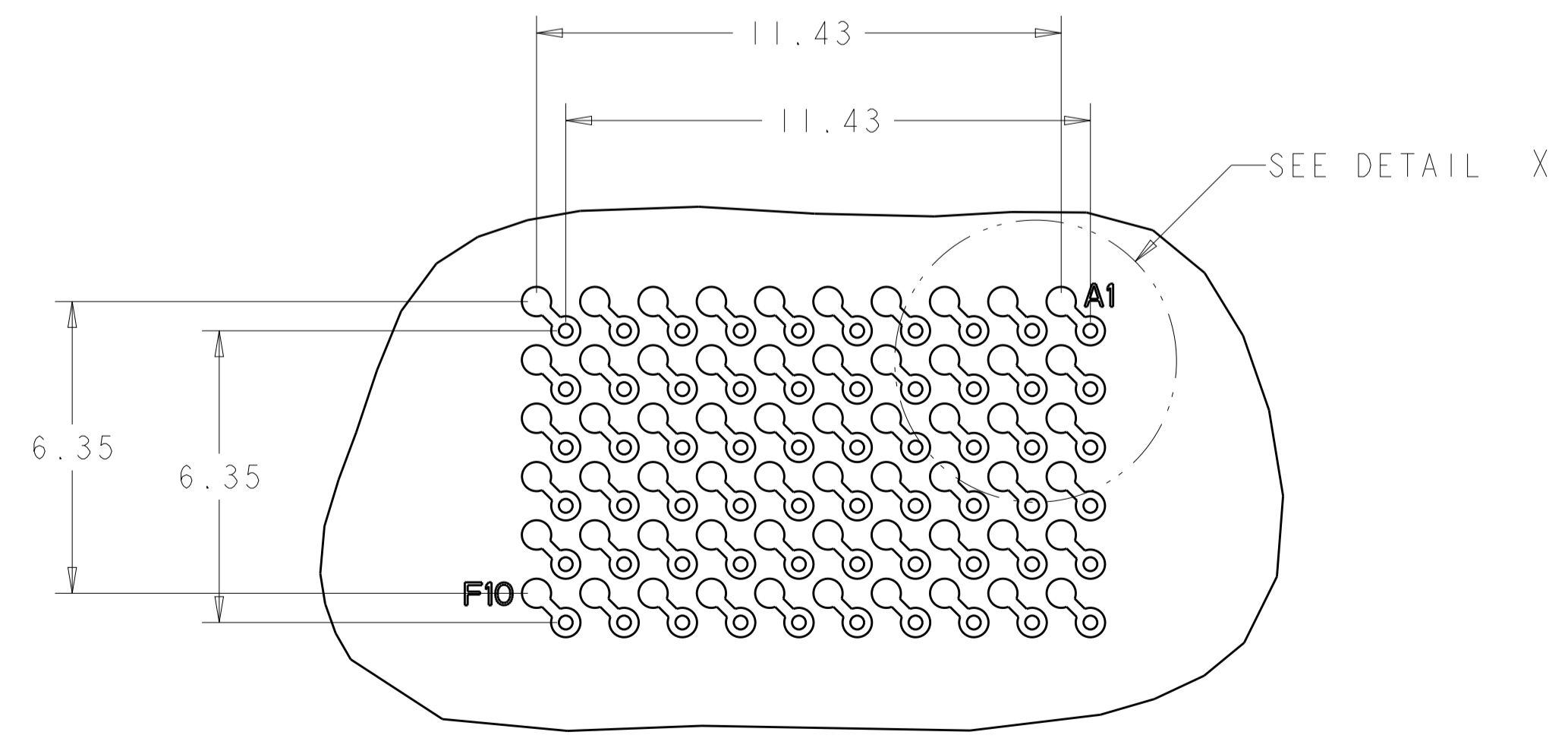
LOC		DIST		REVISIONS				
P	LTN	DESCRIPTION	DATE	DWN	APVD			
C		REVISED PER ECO 12-021576	12-18-12	CT	DH			



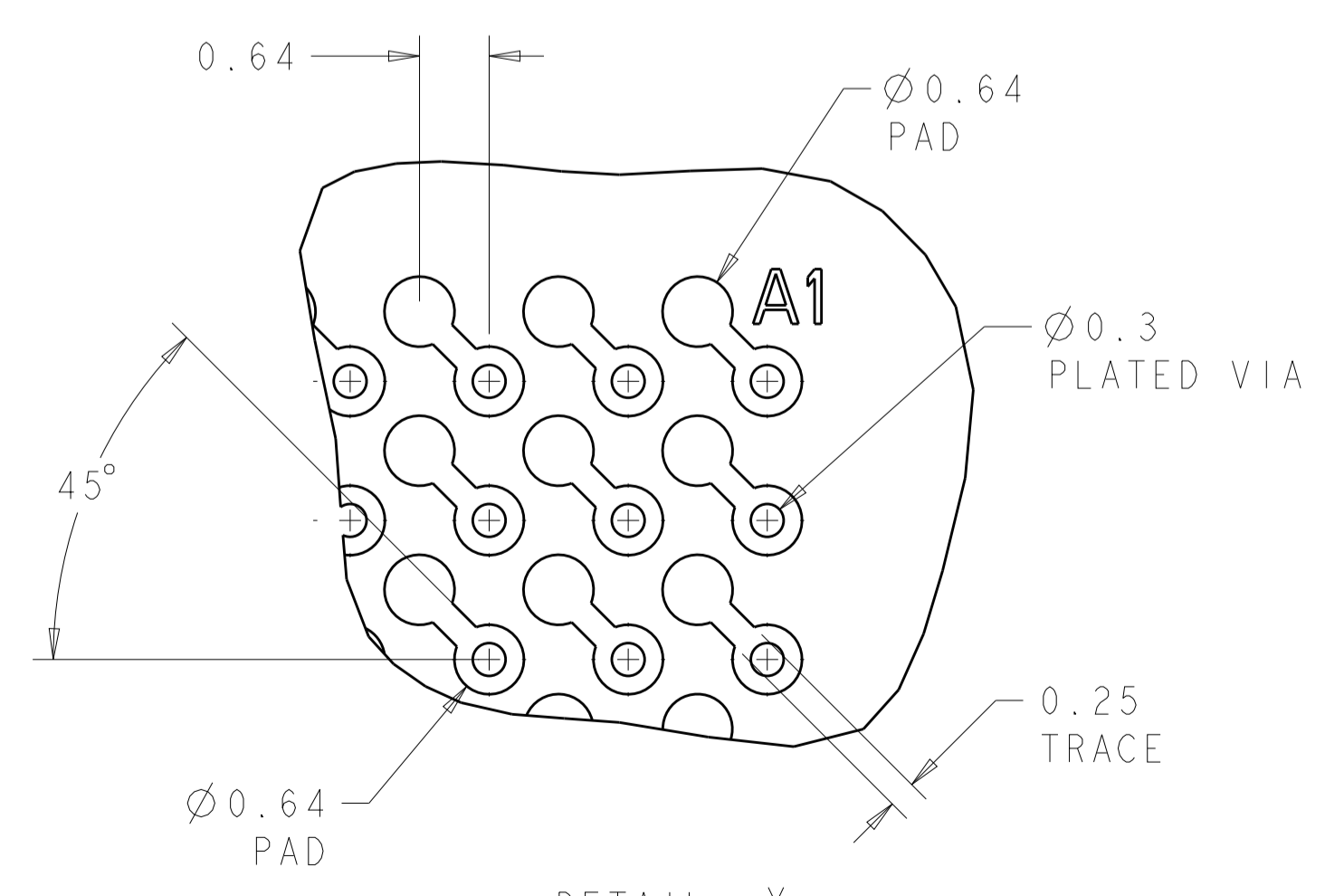
END VIEW OF 2102080-9 THRU 1-2102080-2



△ MATERIAL: HOUSINGS; LCP, COLOR-NATURAL CONTACT; BERYLLIUM COPPER SOLDER BALL; SEE TABLE TAPE, FILM; KAPTON WITH SILICON ADHESIVE
 △ FINISH: CONTACT; GOLD (SEE TABLE) ON MATING AREA OVER NICKEL ON ENTIRE CONTACT.



PCB LAYOUT (CONNECTOR SIDE) SCALE 8:1



DETAIL X SCALE 16:1

MATING PART NUMBER	MATED STACK HEIGHT (mm)	GOLD PLATING THICKNESS	H MAX REF	SOLDER BALL MATERIAL	PART NUMBER
2102079-4	12	0.76 μ m	8	LEAD FREE PER SAC405	2102080-8
2102079-3	12	0.76 μ m	8	TIN LEAD	2102080-7
2102079-4	10	0.76 μ m	6	LEAD FREE PER SAC405	2102080-6
2102079-3	10	0.76 μ m	6	TIN LEAD	2102080-5
2102079-2	12	1.27 μ m	8	LEAD FREE PER SAC405	2102080-4
2102079-1	12	1.27 μ m	8	TIN LEAD	2102080-3
2102079-2	10	1.27 μ m	6	LEAD FREE PER SAC405	2102080-2
2102079-1	10	1.27 μ m	6	TIN LEAD	2102080-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm

TOLERANCES UNLESS OTHERWISE SPECIFIED:

0 PLC	±
1 PLC	±0.13
2 PLC	±
3 PLC	±
4 PLC	±
ANGLES	±

MATERIAL: FINISH:

APPROVED:

DATE: 23 JUL 2009

NAME: ASSEMBLY, SOCKET, 60 POSITION, MEZALOK STACKING CONNECTOR

SIZE: A1

SCALE: 10:1

SHEET: 1 OF 1

REV: C